IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co-packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Field Stop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Case Temperature in IH Cooker Application
- Low Gate Charge
- These are Pb-Free Devices

Typical Applications

- Inductive Heating
- Consumer Appliances
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I _C	80 40	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	320	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	I _F	80 40	А
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	320	А
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	260 104	W
Operating junction temperature range	TJ	-55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

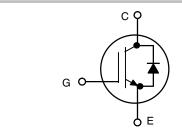
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

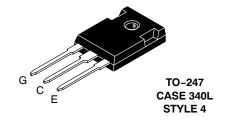


ON Semiconductor®

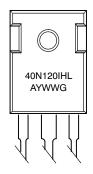
http://onsemi.com

40 A, 1200 V **V_{CEsat}** = 1.90 **V** $E_{off} = 1.40 \text{ mJ}$





MARKING DIAGRAM



= Assembly Location

= Year WW = Work Week = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB40N120IHLWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.48	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.5	°C/W
Thermal resistance junction-to-ambient	R_{\thetaJA}	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC				•		
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V, I}_{C} = 500 \mu\text{A}$	V _{(BR)CES}	1200	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 40 A V _{GE} = 15 V, I _C = 40 A, T _J = 150°C	V _{CEsat}	-	1.90 2.1	2.35	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$, $I_C = 400 \mu A$	V _{GE(th)}	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 150°C	I _{CES}	-	- -	0.5 2.0	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	-	200	nA
DYNAMIC CHARACTERISTIC						
Input capacitance		C _{ies}	-	10400	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	245	-	
Reverse transfer capacitance		C _{res}	-	185	-	
Gate charge total		Q_g		420		nC
Gate to emitter charge	V _{CE} = 600 V, I _C = 40 A, V _{GE} = 15 V	Q _{ge}		95		
Gate to collector charge		Q _{gc}		178		
SWITCHING CHARACTERISTIC, INDUCT	TIVE LOAD					
Turn-off delay time	T _J = 25°C	t _{d(off)}		360		ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 40 \text{ A}$ $R_{c} = 10 \Omega$	t _f		130		
Turn-off switching loss	$R_g = 10 \Omega$ $V_{GE} = 0 \text{ V} / 15 \text{V}$	E _{off}		1.40		mJ
Turn-off delay time	T _J = 125°C	t _{d(off)}		380		ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 40 \text{ A}$ $R_{q} = 10 \Omega$	t _f		185		
Turn-off switching loss	V _{GE} = 0 V/ 15V	E _{off}		2.6		mJ
DIODE CHARACTERISTIC						_
Forward voltage	V _{GE} = 0 V, I _F = 40 A V _{GE} = 0 V, I _F = 40 A, T _J = 150°C	V _F		1.6 1.8	1.8	V

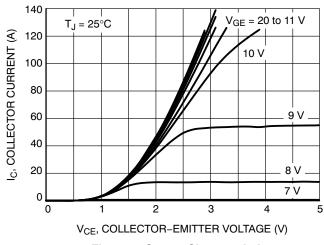


Figure 1. Output Characteristics

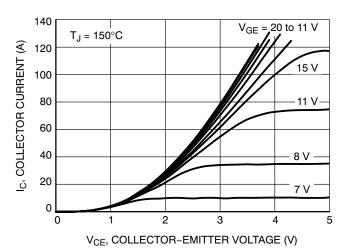


Figure 2. Output Characteristics

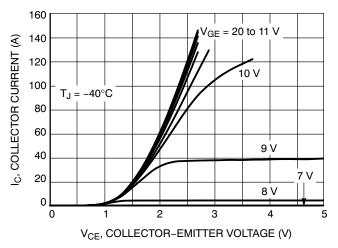


Figure 3. Output Characteristics

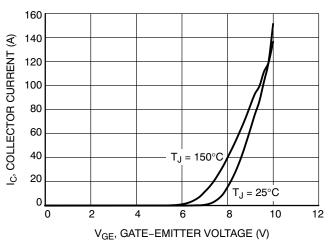


Figure 4. Typical Transfer Characteristics

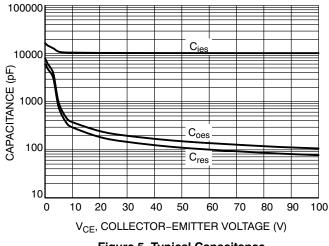


Figure 5. Typical Capacitance

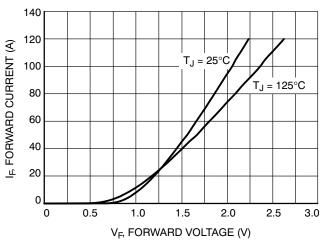
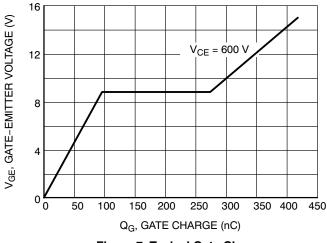


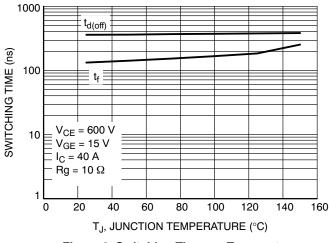
Figure 6. Diode Forward Characteristics



(m) V_{CE} = 600 V Eoff, TURN-OFF SWITCHING LOSS 3 $V_{GE} = 15 V$ $I_C = 40 A$ 2.5 $Rg = 10 \Omega$ 2 1.5 0.5 00 100 120 140 T_J, JUNCTION TEMPERATURE (°C)

Figure 7. Typical Gate Charge

Figure 8. Energy Loss vs. Temperature



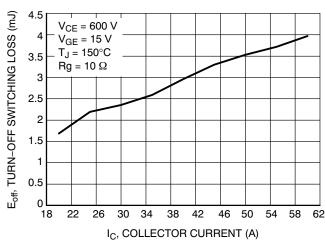
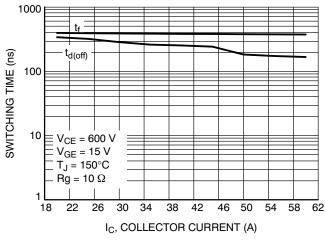


Figure 9. Switching Time vs. Temperature

Figure 10. Energy Loss vs. I_C



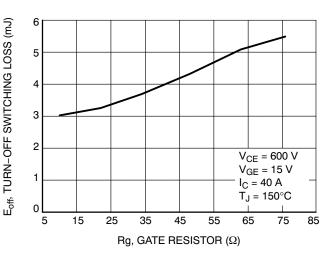


Figure 11. Switching Time vs. I_C

Figure 12. Energy Loss vs. Rg

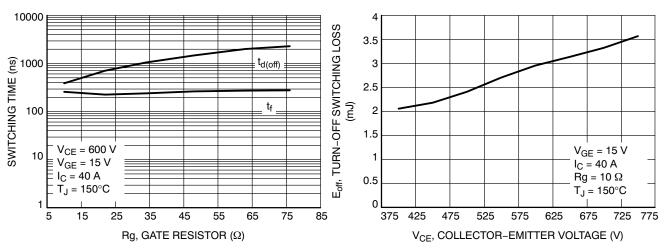


Figure 13. Switching Time vs. Rg

Figure 14. Energy Loss vs. V_{CE}

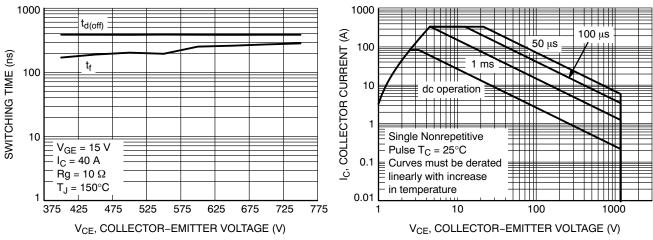


Figure 15. Switching Time vs. V_{CE}

Figure 16. Safe Operating Area

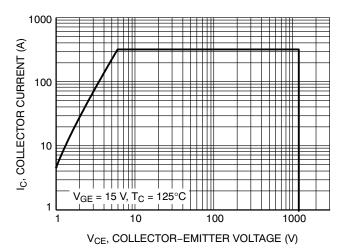


Figure 17. Reverse Bias Safe Operating Area

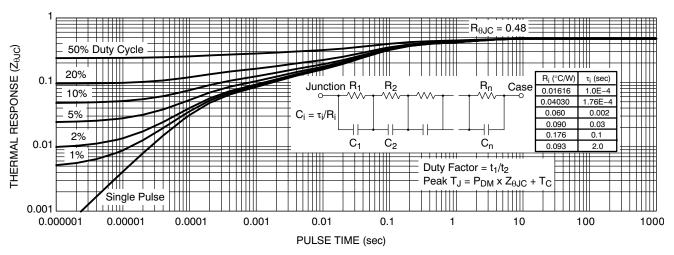


Figure 18. IGBT Transient Thermal Impedance

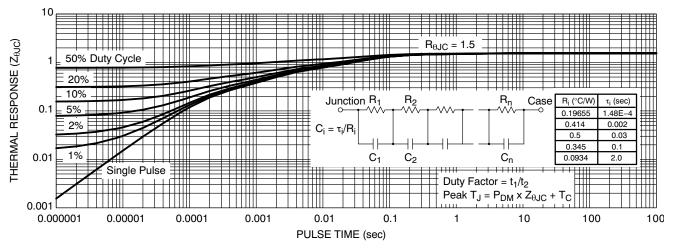


Figure 19. Diode Transient Thermal Impedance

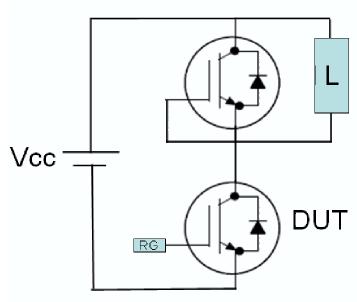


Figure 20. Test Circuit for Switching Characteristics

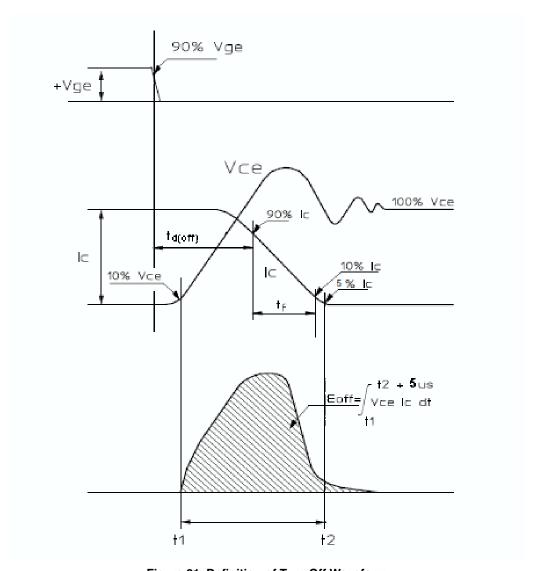
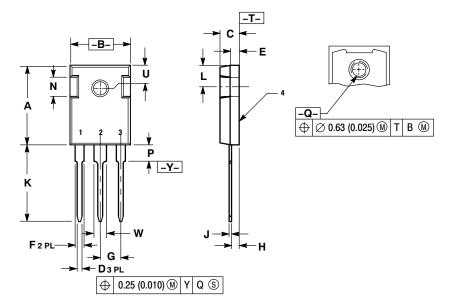


Figure 21. Definition of Turn Off Waveform

PACKAGE DIMENSIONS

TO-247 CASE 340L-02 ISSUE F



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	20.32	21.08	0.800	8.30	
В	15.75	16.26	0.620	0.640	
С	4.70	5.30	0.185	0.209	
D	1.00	1.40	0.040	0.055	
Е	1.90	2.60	0.075	0.102	
F	1.65	2.13	0.065	0.084	
G	5.45 BSC		0.215 BSC		
Н	1.50	2.49	0.059	0.098	
J	0.40	0.80	0.016	0.031	
K	19.81	20.83	0.780	0.820	
L	5.40	6.20	0.212	0.244	
N	4.32	5.49	0.170	0.216	
Р		4.50		0.177	
Q	3.55	3.65	0.140	0.144	
U	6.15 BSC 0.242 BS		BSC		
W	2.87	3.12	0.113	0.123	

STYLE 4: PIN 1. GATE

- 2. COLLECTOR 3. EMITTER

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